

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1266	257/686.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:22
L2	265	1 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:26
L3	825	257/723.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:34
L4	260	3 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:34
L5	981	257/777.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:39
L6	195	5 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:39
L7	1506	257/778.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:43
L8	540	7 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:43
L9	286	257/782.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:43

L10	791	257/784.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:43
L11	255	10 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 16:43
L12	1230	257/787.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:20
L13	515	12 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:20
L14	317	257/773.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:29
L15	236	257/673.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:41
L16	527	257/786.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:49
L17	206	16 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 17:49
L18	1142	257/737.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:02
L19	363	18 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:03

L20	1128	257/738.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:12
L21	398	20 and (@ad<="19991215" @pd<="19991215" @rlad<="19991215")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:12
L22	50	257/E25.006 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:44
L23	84	257/E25.013 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:44
L24	20	257/E25.018 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:44
L25	23	257/E25.021 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:45
L26	32	257/E25.027 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 18:45
L29	26	257/E21.614 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:22
L30	89	257/E23.085 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:22
L31	17	257/E31.117 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:43

L32	6	257/E31.118 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:43
L33	4	257/E51.02 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:43
L34	54	257/E23.116 and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/22 19:44
S1	79	Ohuchi-Shinji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 23:17
S2	758	Yamada-Shigeru.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 23:28
S3	170	Shiraishi-Yasushi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 23:28
S4	317	257/685.ccls. and (chip die) same (seal\$3 mold\$3 encapsulant encapsulat\$3) same (bump ball terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 23:35

5/ 22/ 09 8:09:39 PM

C:\Documents and Settings\ DNguyen14\ My Documents\ EAST\ Workspaces\ 10657139.wsp